

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE0117AK uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

V_{DS} =100V,I_D =17A

 $R_{DS(ON)} < 48m\Omega$ @ $V_{GS}=10V$ (Typ:42m Ω)

 $R_{DS(ON)} < 53m\Omega$ @ V_{GS} =4.5V (Typ:44m Ω)

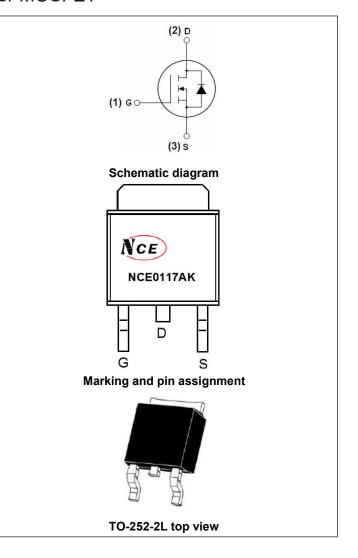
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits

100% UIS TESTED!

100% AVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE0117AK	NCE0117AK	TO-252-2L	-	-	-

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I _D	17	А
Drain Current-Continuous(T _C =100 ℃)	I _D (100℃)	12	А
Pulsed Drain Current	I _{DM}	60	А
Maximum Power Dissipation	P _D	55	W
Single pulse avalanche energy (Note 5)	E _{AS}	29	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$ C



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NCE0117AK

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	Rejc	2.73	°C/W	l
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	100	110	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)				•		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.2	1.6	2.5	V
D : 0		V _{GS} =10V, I _D =10A	-	42	48	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =8A		44	53	mΩ
Forward Transconductance	g FS	V _{DS} =10V,I _D =10A	-	14	-	S
Dynamic Characteristics (Note4)	-	,	'			
Input Capacitance	C _{lss}	., 50,414 014	-	1468	-	PF
Output Capacitance	Coss	$V_{DS}=50V, V_{GS}=0V,$	-	62	-	PF
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	13.6	-	PF
Switching Characteristics (Note 4)	-	,	•			
Turn-on Delay Time	t _{d(on)}		-	13.8	-	nS
Turn-on Rise Time	t _r	$V_{DD}=30V,R_{L}=15\Omega$	-	9.3	-	nS
Turn-Off Delay Time	$t_{\sf d(off)}$	V_{GS} =10V, R_{G} =2.5 Ω	-	43.8	-	nS
Turn-Off Fall Time	t _f		-	11.4	-	nS
Total Gate Charge	Qg)/ 50\/ L 40A	-	40	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =50V,I _D =10A,	-	4.4	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	9.5	-	nC
Drain-Source Diode Characteristics	-		•		•	
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =17A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	17	Α
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is neg	ligible (tur	n-on is de	ominated b	y LS+LD)

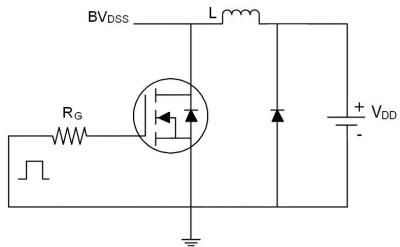
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V,L=0.5mH,Rg=25 Ω

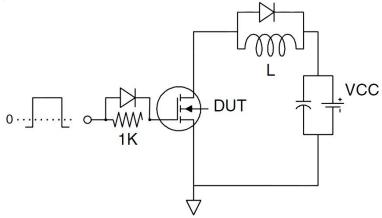


Test Circuit

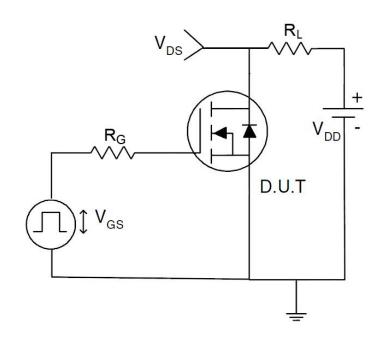
1) E_{AS} test Circuit



2) Gate charge test Circuit

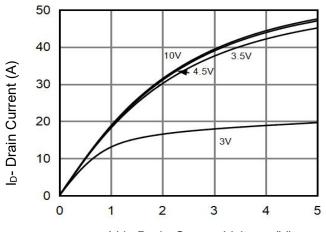


3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)



Vds Drain-Source Voltage (V)



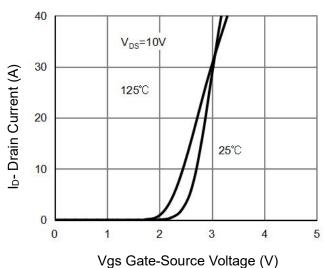


Figure 2 Transfer Characteristics

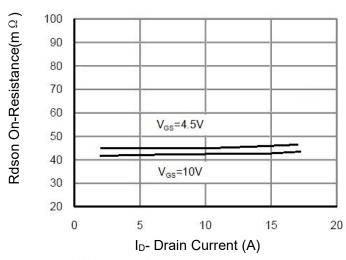


Figure 3 Rdson- Drain Current

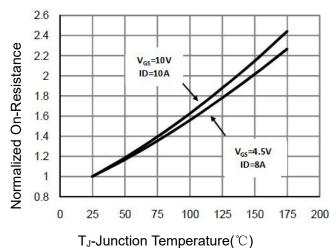


Figure 4 Rdson-JunctionTemperature

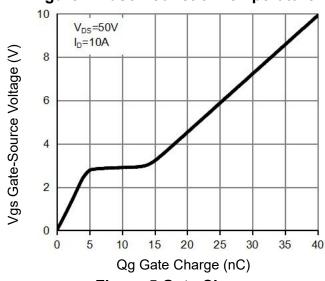


Figure 5 Gate Charge

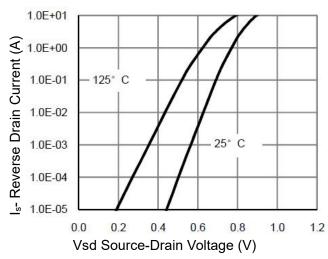


Figure 6 Source- Drain Diode Forward



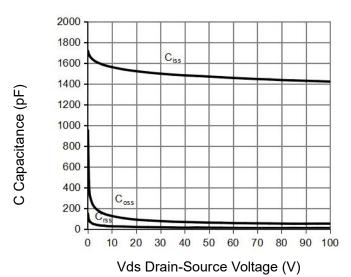


Figure 7 Capacitance vs Vds

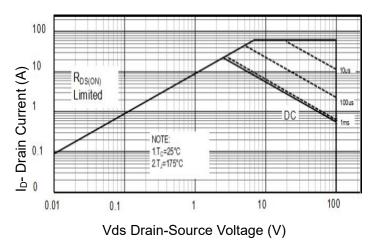


Figure 8 Safe Operation Area

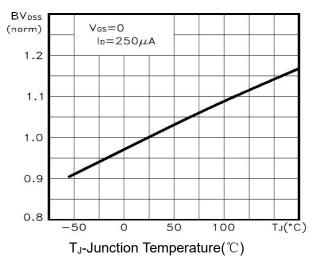


Figure 9 BV_{DSS} vs Junction Temperature

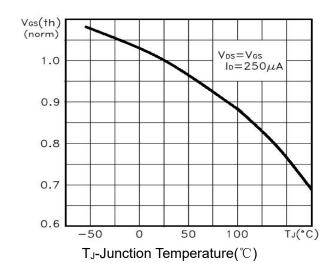


Figure 10 V_{GS(th)} vs Junction Temperature

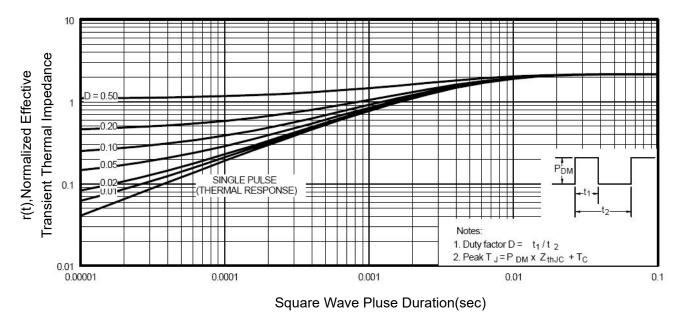
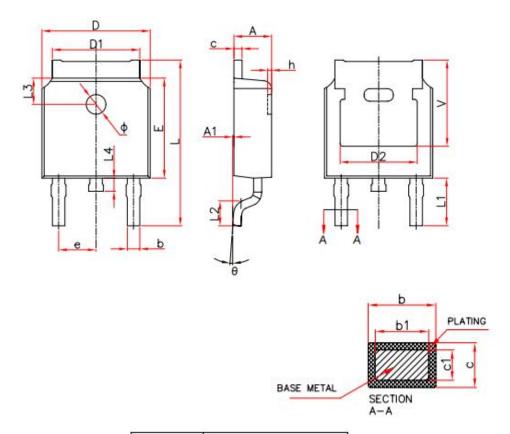


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-252-2L Package Information



Cumbal	Millimeters			
Symbol	Min.	Max.		
Α	2.20	2.40		
A1	0.00	0.13		
b	0.66	0.86		
b1	0.73	0.79		
С	0.46	0.58		
c1	0.50	0.52		
D	6.50	6.70		
D1	5.10	5.46		
D2	4.83 REF.			
E	6.00	6.20		
е	2.19	2.39		
L	9.80	10.40		
L1	2.90 REF.			
L2	1.40	1.70		
L3	1.60 REF.			
L4	0.60	1.00		
Ф	1.10	1.30		
θ	0°	8°		
h	0.00	0.30		
V	5.35	REF.		

NCE0117AK

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